

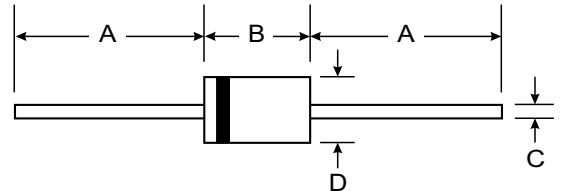
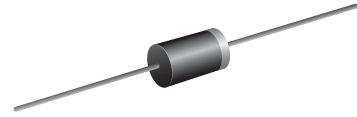
VOLTAGE RANGE: 1500V
CURRENT: 3.0 A

Features

- High temperature metallurgically bonded construction
- Sintered glass cavity free junction
- Capability of meeting environmental standard of MIL-S-19500
- High temperature soldering guaranteed
- 350°C /10sec/0.375"lead length at 5 lbs tension
- Operate at Ta =55°C with no thermal run away
- Typical Ir<0.1μA

Mechanical Data

- Case: DO-201AD, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 1.2 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



DO-201AD		
Dim	Min	Max
A	25.40	—
B	7.20	9.50
C	1.20	1.30
D	4.80	5.30
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	SYMBOL	BY228GP	units
Maximum Recurrent Peak Reverse Voltage	V _{rrm}	1500	V
Maximum RMS Voltage	V _{rms}	1050	V
Maximum DC blocking Voltage	V _{dc}	1500	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	I _{f(av)}	3.0	A
Peak Forward Surge Current 8.3ms single Half sine-wave superimposed on rated load	I _{fsm}	125.0	A
Maximum Instantaneous Forward Voltage At 5.0A	V _f	1.50	V
Maximum full load reverse current full cycle Average at 55°C	I _{r(av)}	100.0	μA
Maximum DC Reverse Current at rated DC blocking voltage	I _r	5.0 100.0	μA μA
Typical Reverse Recovery Time (Note 1)	T _{rr}	1000	nS
Typical Thermal Resistance (Note 2)	R _{th(ja)}	70.0	K/W
Storage and Operating Junction Temperature	T _{stg, Tj}	-65 to +175	°C

Note:

1. Reverse Recovery Condition I_f =0.5A, I_r =1.0A, I_{rr} =0.25A
2. Thermal Resistance from Junction to Ambient on PC board with spacing 25mm

RATINGS AND CHARACTERISTIC CURVES BY228GP

